

October 2012 SuperFET® II

FCD380N60E 600V N-Channel MOSFET

Features

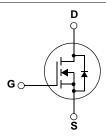
- 650V @T_J = 150°C
- Max. $R_{DS(on)} = 380 m\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 34nC)
- Low Effective Output Capacitance (Typ. C_{oss}.eff = 97pF)
- 100% Avalanche Tested

Description

SuperFET[®]II is, Fairchild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET®II is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		FCD380N60E	Units
V _{DSS}	Drain to Source Voltage			600	V
V	Cata to Source Voltage	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f > 1Hz)	±30	V
1	Drain Current	-Continuous (T _C = 25°C)		10.2	۸
I _D Drain Current		-Continuous (T _C = 100°C)		6.4	Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	30.6	Α
E _{AS}	Single Pulsed Avalanche En	ergy	(Note 2)	211.6	mJ
I _{AR}	Avalanche Current		(Note 1)	2.3	Α
E _{AR}	Repetitive Avalanche Energy	1	(Note 1)	1.06	mJ
d. /dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
dv/dt	MOSFET dv/dt			100	V/IIS
D	Dower Dissinction	$(T_C = 25^{\circ}C)$		106	W
P_{D}	Power Dissipation	- Derate above 25°C		0.85	W/°C
T _J , T _{STG}	Operating and Storage Temp	perature Range		-55 to +150	°C
T _L	Maximum Lead Temperature 1/8" from Case for 5 Second	•		300	°C

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCD380N60E	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.18	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	100	*C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCD380N60E	FCD380N60E	D-PAK	380mm	16mm	2500

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	cteristics					
B\/	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 25^{\circ}C$	600	-	-	V
BV _{DSS} Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 150$ °C	650	-	-	V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10mA, Referenced to 25°C	-	0.67	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V, I_D = 10A$	-	700	-	V
	Zero Gate Voltage Drain Current	$V_{DS} = 480V, V_{GS} = 0V$	-	-	5	μА
DSS	Zero Gale Vollage Drain Guirent	$V_{DS} = 480V, T_{C} = 125^{\circ}C$	-	-	20	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 5A$	-	0.32	0.38	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 20V, I_{D} = 5A$	-	10	-	S

Dynamic Characteristics

•						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V		1330	1770	pF
C _{oss}	Output Capacitance			945	1260	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/12	-	60	90	pF
C _{oss}	Output Capacitance	$V_{DS} = 380V, V_{GS} = 0V, f = 1.0MHz$	-	25	-	pF
Coss eff.	Effective Output Capacitance	$V_{DS} = 0V \text{ to } 480V, V_{GS} = 0V$	-	97	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	34	45	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 380V, I_{D} = 5A$	-	5.3	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10V (Note 4)	-	13	-	nC
ESR	Equivalent Series Resistance	Drain open	-	6	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	17	44	ns
t _r	Turn-On Rise Time	$V_{DD} = 380V, I_{D} = 5A$		-	9	28	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_G = 4.7\Omega$		-	64	138	ns
t _f	Turn-Off Fall Time		(Note 4)	-	10	30	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	10.2	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	30.6	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V$, $I_{SD} = 5A$	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 5A	-	240	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	3	-	μС

Notes

- ${\bf 1.}\ {\bf Repetitive}\ {\bf Rating:}\ {\bf Pulse}\ {\bf width}\ {\bf limited}\ {\bf by}\ {\bf maximum}\ {\bf junction}\ {\bf temperature}$
- 2. I $_{AS}$ = 2.3A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C
- 3. $I_{SD} \le 5.1 A$, di/dt $\le 200 A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

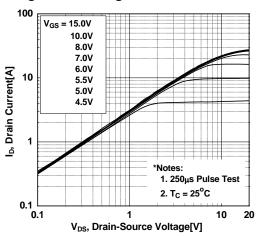


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

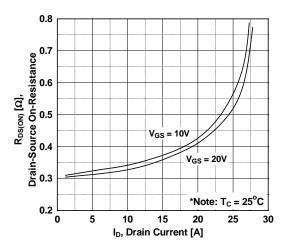


Figure 5. Capacitance Characteristics

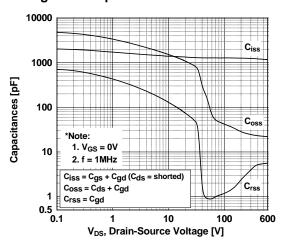


Figure 2. Transfer Characteristics

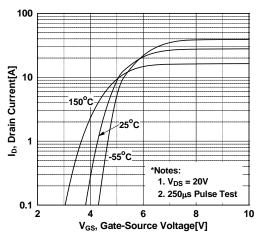


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

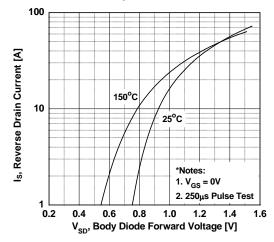
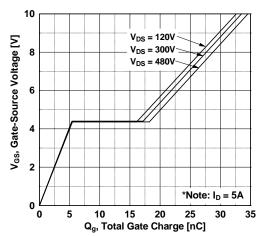


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

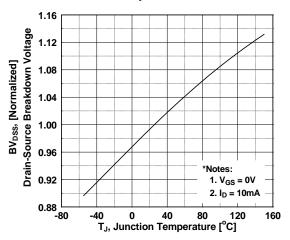


Figure 9. Maximum Safe Operating Area vs. Case Temperature

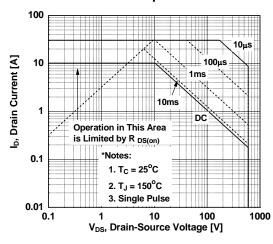


Figure 8. On-Resistance Variation vs. Temperature

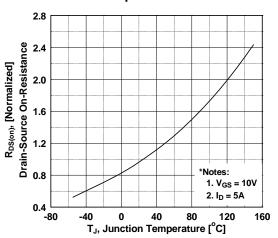


Figure 10. Maximum Drain Current

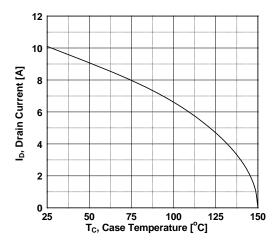
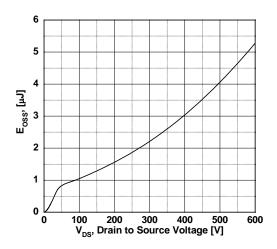
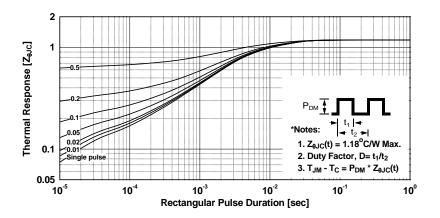


Figure 11. Eoss vs. Drain to Source Voltage Switching Capability

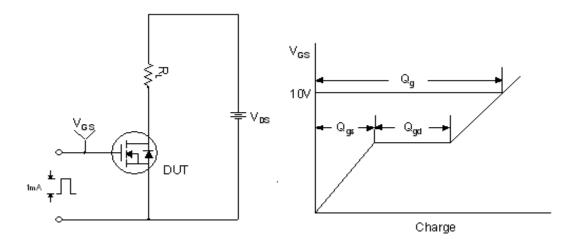


Typical Performance Characteristics (Continued)

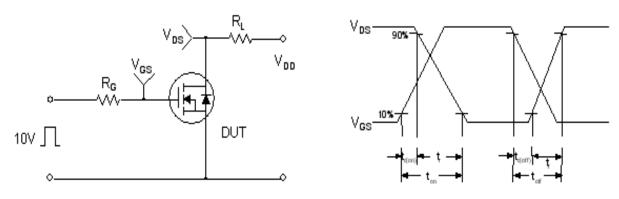
Figure 12. Transient Thermal Response Curve



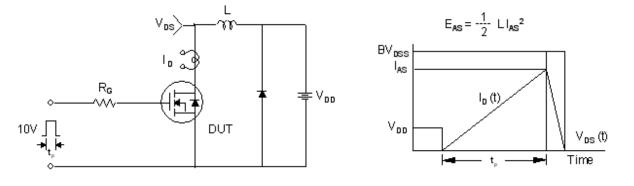
Gate Charge Test Circuit & Waveform



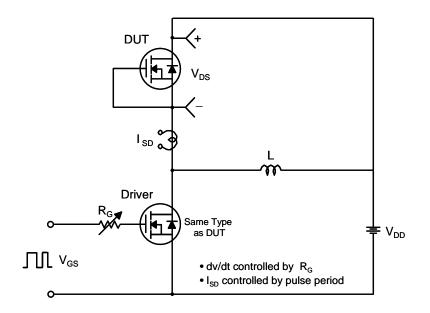
Resistive Switching Test Circuit & Waveforms

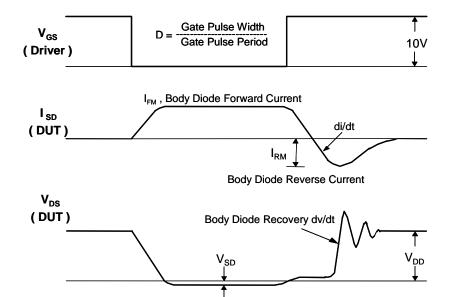


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

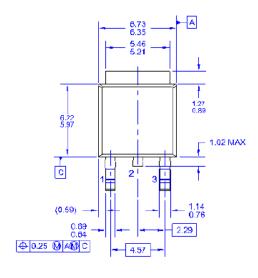


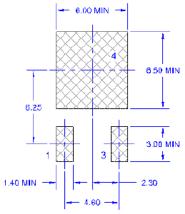


Body Diode Forward Voltage Drop

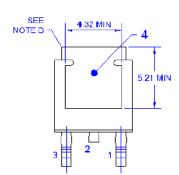
Mechanical Dimensions

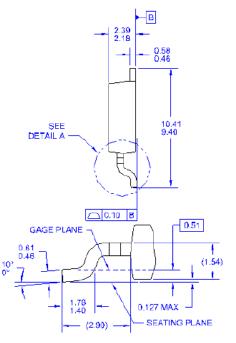
D-PAK





LAND PATTERN RECOMMENDATION





- NOTES: LINLESS OTHERWISE SPECIFIED

 A) THIS PACKAGE CONFORMS TO JEDEC, TO-252.
 ISSUE C, VARIATION AA.

 B) ALL DINEMSIONS ARE IN MILLIMETERS.
 C) DINEMSIONING AND TOLENANCING PER
 ASME Y14.5M-1994.
 D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED
 CORNERS OR EDGE FROTRUSION.
 E) PRESENCE OF TRIMMED CENTER LEAD
 IS OPTIONAL
 F) DIMENSIONS ARE EXCLUSRIVE OF BURSS,
 MOLD FLASH AND THE BAR EXTRUSIONS.
 B) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD
 TO220P1003X295-3N.
- TO220P1003X239-3N, H: DRAWING NUMBER AND REVISION: WKT-TO252A03REVB

Dimensions in Millimeters





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